

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.85	100.0	2.9
			<b>Subtotal</b>	<b>0.85</b>	<b>100</b>	<b>2.9</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04	100.0	0.14
			<b>Subtotal</b>	<b>0.04</b>	<b>100</b>	<b>0.14</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	3.51	100.0	12
			<b>Subtotal</b>	<b>3.51</b>	<b>100</b>	<b>12</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.05
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02	0.03	0.05
	Copper alloy	Iron (Fe)	7439-89-6	0.05	0.1	0.17
	Copper alloy	Copper (Cu)	7440-50-8	50.85	99.84	173.92
			<b>Subtotal</b>	<b>50.94</b>	<b>100</b>	<b>174.19</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.62	6.0	8.96
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.06	7.0	10.45
	Filler	Silica fused	60676-86-0	37.54	86.0	128.4
	Carbon Black	Carbon black	1333-86-4	0.44	1.0	1.49
			<b>Subtotal</b>	<b>43.66</b>	<b>100</b>	<b>149.3</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.22	100.0	0.75
			<b>Subtotal</b>	<b>0.22</b>	<b>100</b>	<b>0.75</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	2.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0.02	2.5	0.07
	Lead alloy	Lead (Pb)	7439-92-1	0.76	95.5	2.61
			<b>Subtotal</b>	<b>0.8</b>	<b>100</b>	<b>2.73</b>
			<b>Total</b>	<b>100.02</b>	<b>100</b>	<b>342.01</b>

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